10-R1126PA010M7-P707F70

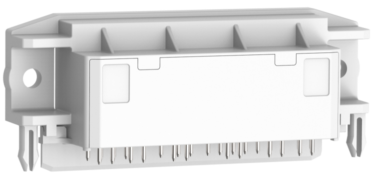
datasheet

***flow*90PACK 1** | **1200 V / 10 A**

Features

- IGBT M7 with low VCEsat and improved EMC behavior
- Supports designs with 90° mounting angle between heatsink and PCB
- Clip-in PCB mounting

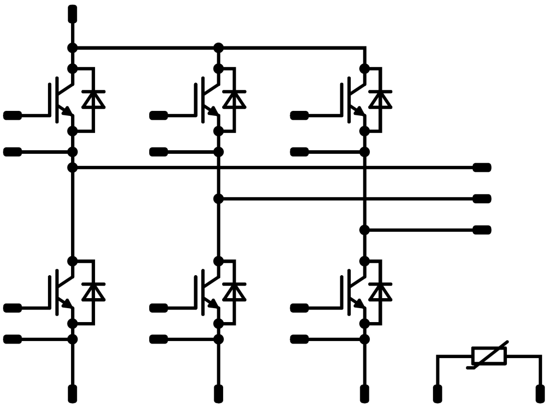
*flow*90 1 housing



Target applications

- Embedded Drives
- Industrial Drives

Schematic



Types

- 10-R1126PA010M7-P707F70

Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Conditions		Value	Unit
Inverter Switch					
Collector-emitter voltage	V_{CES}			1200	V
Collector current	I_C	$T_j = T_{jmax}$	T_s = 80 °C	14	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}		20	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$	T_s = 80 °C	55	W
Gate-emitter voltage	V_{GES}			±20	V
Short circuit ratings	t_{SC}	V_{GE} = 0 V, V_{CC} = 800 V	T_j = 150 °C	9,5	µs
Maximum junction temperature	T_{jmax}			175	°C
Inverter Diode					
Peak repetitive reverse voltage	V_{RRM}			1200	V
Continuous (direct) forward current	I_F	$T_j = T_{jmax}$	T_s = 80 °C	14	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$	T_s = 80 °C	44	W
Maximum junction temperature	T_{jmax}			175	°C

Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Conditions		Value	Unit
Module Properties					
Thermal Properties					
Storage temperature	T_{stg}			-40…+125	°C
Operation temperature under switching condition	T_{jop}			-40…+(T_{jmax} - 25)	°C
Isolation Properties					
Isolation voltage	V_{isol}	DC Test Voltage*	t_p = 2 s	6000	V
Isolation voltage	V_{isol}	AC Voltage	t_p = 1 min	2500	V
Creepage distance				min. 12,7	mm
Clearance				11,84	mm
Comparative Tracking Index	CTI			≥ 200	

*100 % tested in production

Characteristic Values

Parameter	Symbol	Conditions	V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	Unit
Inverter Switch										
Static										
Gate-emitter threshold voltage	$V_{GE(th)}$			10	0,001	25	5,4	6	6,6	V
Collector-emitter saturation voltage	V_{CEsat}		15		10	25 125 150		1,66 1,9 1,96	2,15	V
Collector-emitter cut-off current	I_{CES}		0	1200		25			35	µA
Gate-emitter leakage current	I_{GES}		0	0		25			500	nA
Internal gate resistance	r_g							None		Ω
Input capacitance	C_{ies}		0	10		25		2000		pF
Output capacitance	C_{oes}		0	10		25		86		pF
Reverse transfer capacitance	C_{res}		0	10		25		23		pF
Gate charge	Q_g	V_{CC} = 600 V	15		10	25		80		nC
Thermal										
Thermal resistance junction to sink*	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						1,72		K/W

*Only valid with pre-applied Vincotech thermal interface material.

Parameter	Symbol	Conditions	V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	Unit
Dynamic										
Turn-on delay time	$t_{d(on)}$	R_{gon} = 32 Ω R_{goff} = 32 Ω	±15	600	10	25 125 150		134,4 135,4 134,4		ns
Rise time	t_r	R_{gon} = 32 Ω R_{goff} = 32 Ω	±15	600	10	25 125 150		26 28,6 30,2		ns
Turn-off delay time	$t_{d(off)}$	R_{gon} = 32 Ω R_{goff} = 32 Ω	±15	600	10	25 125 150		171,6 194,4 198,8		ns
Fall time	t_f	R_{gon} = 32 Ω R_{goff} = 32 Ω	±15	600	10	25 125 150		104,63 119,74 122,91		ns
Turn-on energy (per pulse)	E_{on}	Q_{rFWD}=1,04 µC Q_{rFWD}=1,57 µC Q_{rFWD}=1,72 µC	±15	600	10	25 125 150		0,832 1,02 1,08		mWs
Turn-off energy (per pulse)	E_{off}		±15	600	10	25 125 150		0,689 0,91 0,965		mWs

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Inverter Diode										
Static										
Forward voltage	V_F				10	25 125 150		1,61 1,7 1,7	2,1	V
Reverse leakage current	I_R	V_r = 1200 V				25			25	µA
Thermal										
Thermal resistance junction to sink*	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						2,16		K/W
Dynamic										
Peak recovery current	I_{RRM}	d*i*/d*t*=372 A/µs d*i*/d*t*=269 A/µs d*i*/d*t*=274 A/µs	±15	600	10	25 125 150		8,82 9,24 9,27		A
Reverse recovery time	t_{rr}					25 125 150		244,67 357,43 391,19		ns
Recovered charge	Q_r					25 125 150		1,04 1,57 1,72		µC
Reverse recovered energy	E_{rec}					25 125 150		0,351 0,588 0,653		mWs
Peak rate of fall of recovery current	$(di_{rf}/dt)_{max}$					25 125 150		64,71 52,16 48,57		A/µs

*Only valid with pre-applied Vincotech thermal interface material.

Characteristic Values

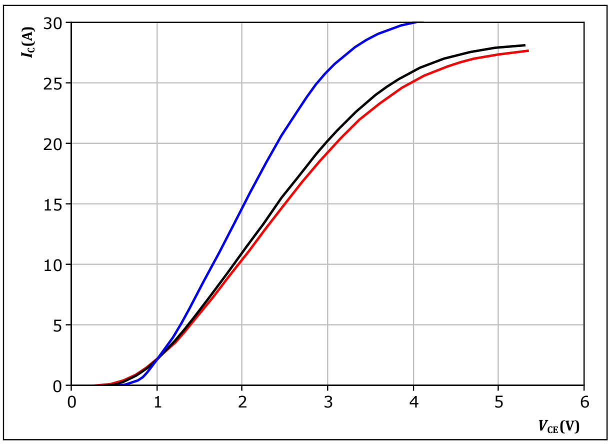
Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Thermistor										
Static										
Rated resistance	R					25		22		kΩ
Deviation of R_{100}	$\Delta_{R/R}$	R_{100} = 1484 Ω				100	-5		5	%
Power dissipation	P							5		mW
Power dissipation constant	d					25		1,5		mW/K
B-value	$B_{(25/50)}$	Tol. ±1 %						3962		K
B-value	$B_{(25/100)}$	Tol. ±1 %						4000		K
Vincotech Thermistor Reference									I	

Inverter Switch Characteristics

figure 1. **IGBT**

Typical output characteristics

I_C = f(V_{CE})

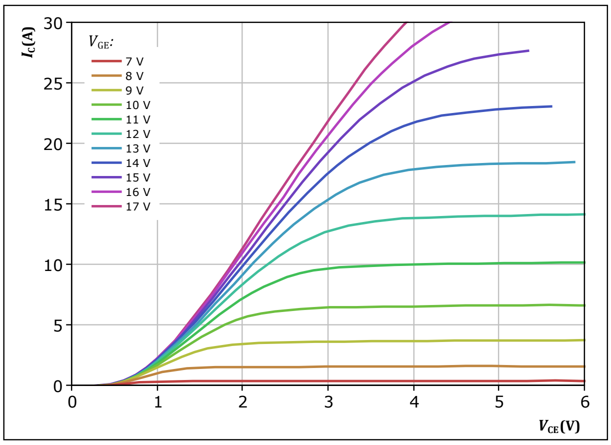


t_p = 250 µs
V_{GE} = 15 V
T_j: 25 °C, 125 °C, 150 °C

figure 2. **IGBT**

Typical output characteristics

I_C = f(V_{CE})

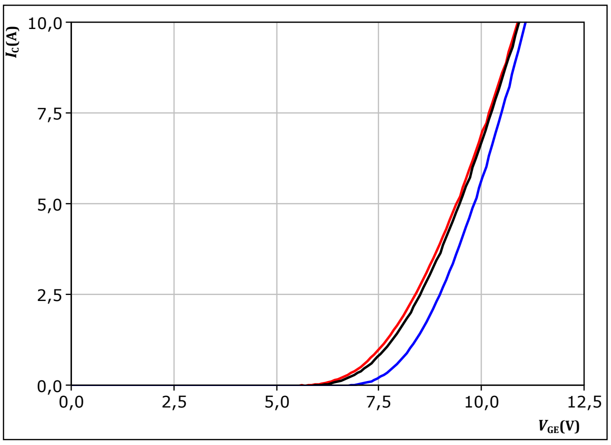


t_p = 250 µs
T_j = 150 °C
V_{GE} from 7 V to 17 V in steps of 1 V

figure 3. **IGBT**

Typical transfer characteristics

I_C = f(V_{GE})

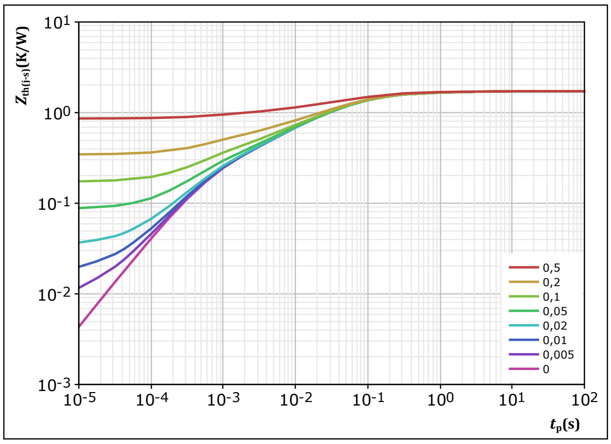


t_p = 250 µs
V_{CE} = 10 V
T_j: 25 °C, 125 °C, 150 °C

figure 4. **IGBT**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)}$ = f(t_p)



D = t_p / T
$R_{th(j-s)}$ = 1,722 K/W

IGBT thermal model values

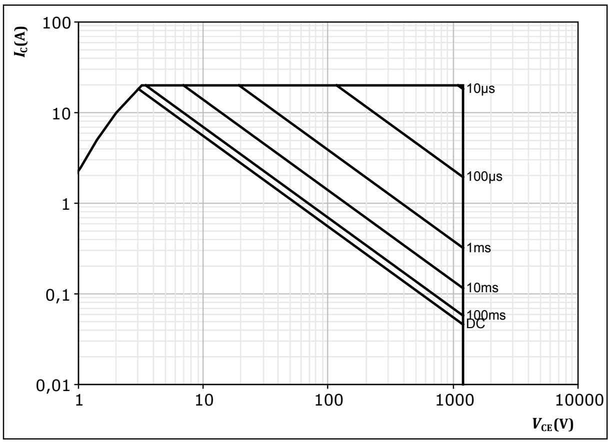
R (K/W)	τ (s)
8,08E-02	2,32E+00
2,21E-01	2,45E-01
6,51E-01	6,03E-02
3,93E-01	1,33E-02
1,95E-01	3,15E-03
1,82E-01	5,45E-04

Inverter Switch Characteristics

figure 5. **IGBT**

Safe operating area

I_C = f(V_{CE})



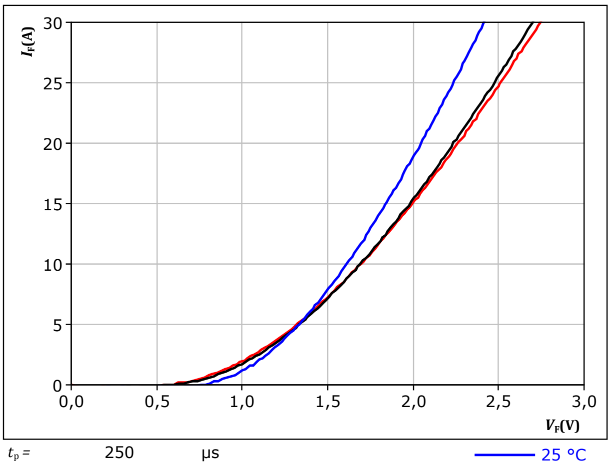
D =	single pulse	
T_s =	80	°C
V_{GE} =	15	V
T_j =	T_{jmax}	

Inverter Diode Characteristics

figure 6. **FWD**

Typical forward characteristics

$I_F = f(V_F)$



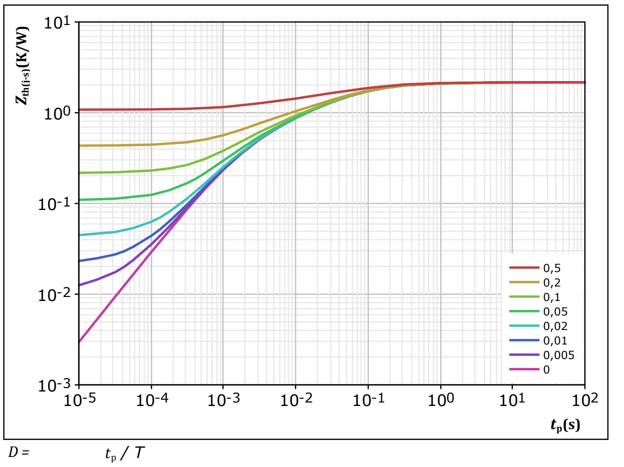
t_p = 250 µs

T_j: 25 °C, 125 °C, 150 °C

figure 7. **FWD**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)} = f(t_p)$



$D = t_p / T$

$R_{th(j-s)}$ = 2,162 K/W

IGBT thermal model values

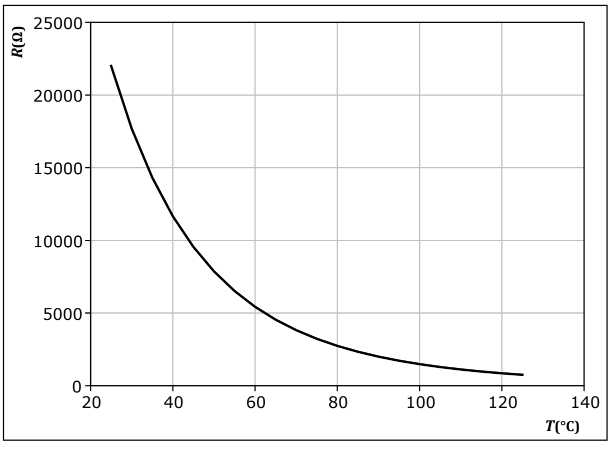
R (K/W)	τ (s)
9,29E-02	2,25E+00
3,88E-01	2,05E-01
7,75E-01	5,06E-02
5,89E-01	8,88E-03
3,17E-01	1,48E-03

Thermistor Characteristics

figure 8.	Thermistor

Typical NTC characteristic as function of temperature

$R_T = f(T)$

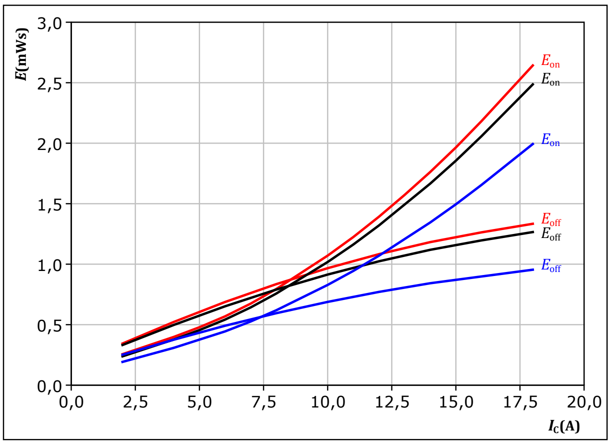


Inverter Switching Characteristics

figure 9. IGBT

Typical switching energy losses as a function of collector current

E = f(I_C)



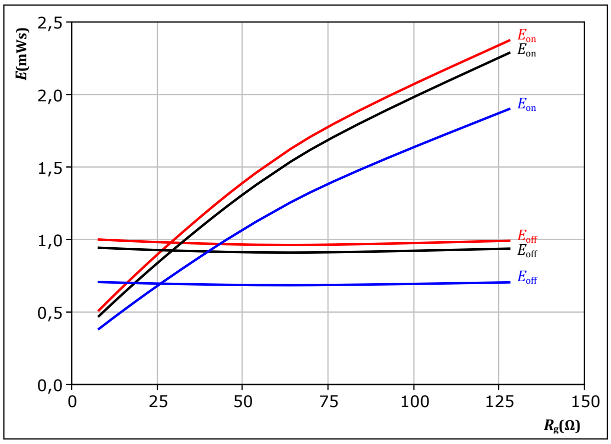
With an inductive load at

V_{CE} =	600	V	T_j: 25 °C / 125 °C / 150 °C
V_{GE} =	±15	V	
R_{gon} =	32	Ω	
R_{goff} =	32	Ω	

figure 10. IGBT

Typical switching energy losses as a function of gate resistor

E = f(R_g)



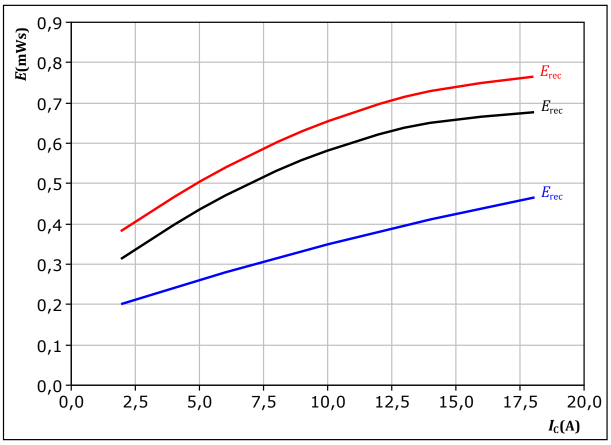
With an inductive load at

V_{CE} =	600	V	T_j: 25 °C / 125 °C / 150 °C
V_{GE} =	±15	V	
I_C =	10	A	

figure 11. FWD

Typical reverse recovered energy loss as a function of collector current

E_{rec} = f(I_C)



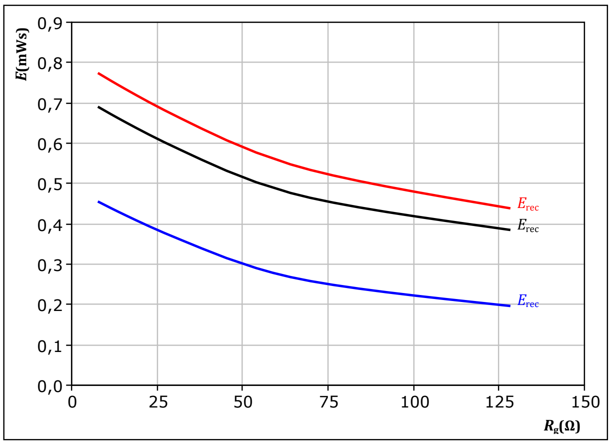
With an inductive load at

V_{CE} =	600	V	T_j: 25 °C / 125 °C / 150 °C
V_{GE} =	±15	V	
R_{gon} =	32	Ω	

figure 12. FWD

Typical reverse recovered energy loss as a function of gate resistor

E_{rec} = f(R_g)



With an inductive load at

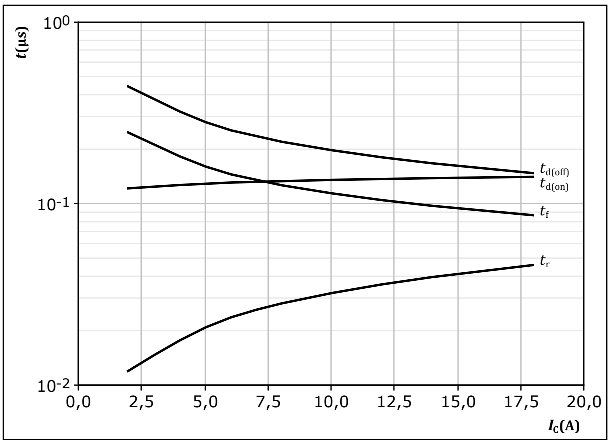
V_{CE} =	600	V	T_j: 25 °C / 125 °C / 150 °C
V_{GE} =	±15	V	
I_C =	10	A	

Inverter Switching Characteristics

figure 13. **IGBT**

Typical switching times as a function of collector current

$t = f(I_C)$



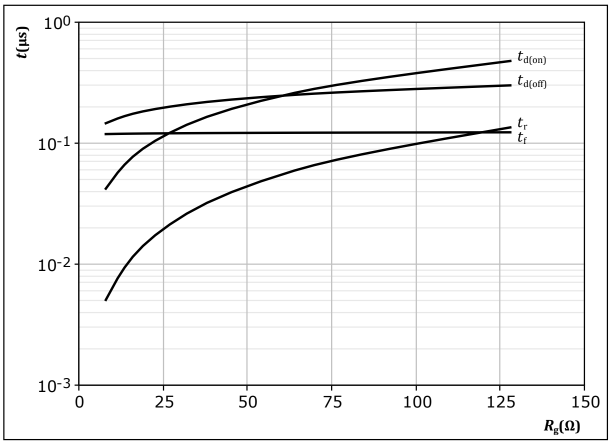
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	32	Ω
R_{goff} =	32	Ω

figure 14. **IGBT**

Typical switching times as a function of gate resistor

$t = f(R_g)$



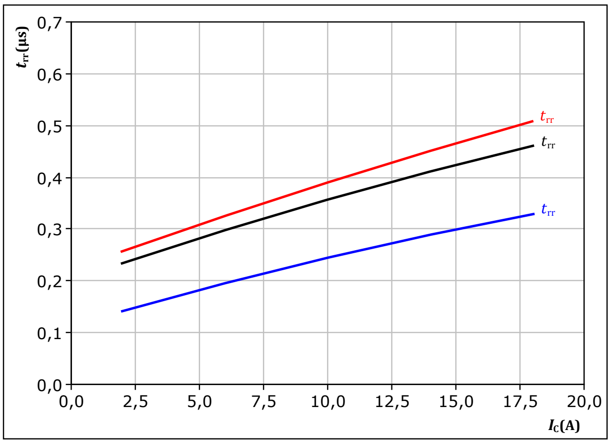
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	10	A

figure 15. **FWD**

Typical reverse recovery time as a function of collector current

$t_{rr} = f(I_C)$



With an inductive load at

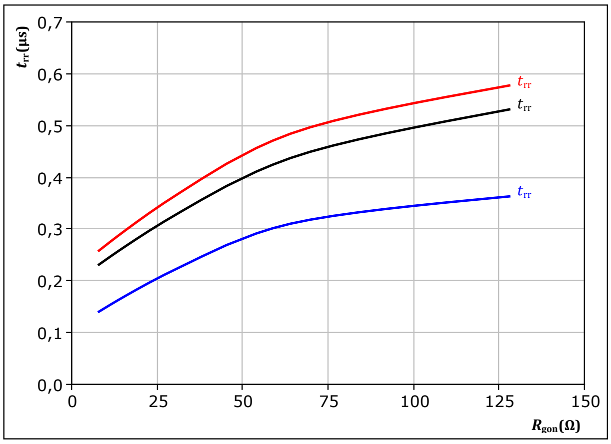
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	32	Ω

T_j: 25 °C, 125 °C, 150 °C

figure 16. **FWD**

Typical reverse recovery time as a function of IGBT turn on gate resistor

$t_{rr} = f(R_{gon})$



With an inductive load at

V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	10	A

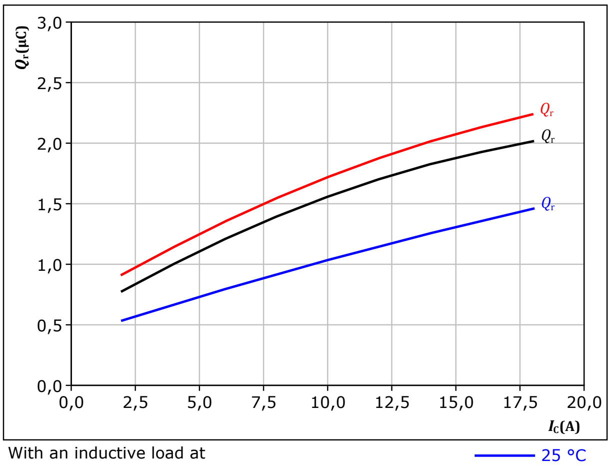
T_j: 25 °C, 125 °C, 150 °C

Inverter Switching Characteristics

figure 17. **FWD**

Typical recovered charge as a function of collector current

Q_r = f(I_C)



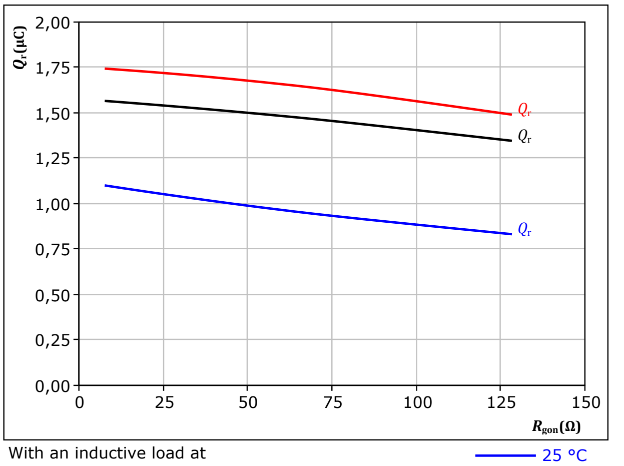
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
R_{gon} =	32	Ω		150 °C

figure 18. **FWD**

Typical recovered charge as a function of turn on gate resistor

Q_r = f(R_{gon})



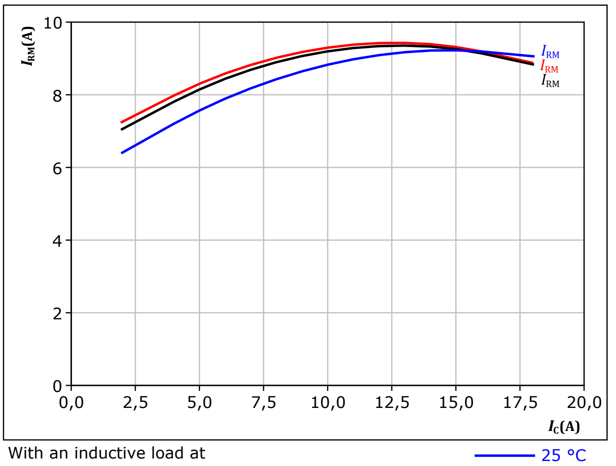
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
I_C =	10	A		150 °C

figure 19. **FWD**

Typical peak reverse recovery current as a function of collector current

I_{RM} = f(I_C)



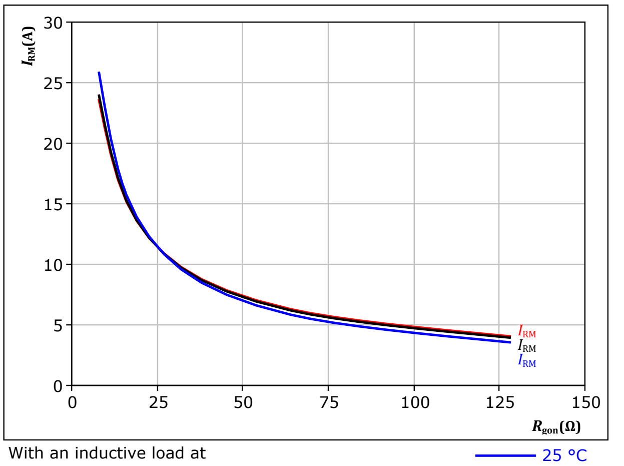
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
R_{gon} =	32	Ω		150 °C

figure 20. **FWD**

Typical peak reverse recovery current as a function of turn on gate resistor

I_{RM} = f(R_{gon})



With an inductive load at

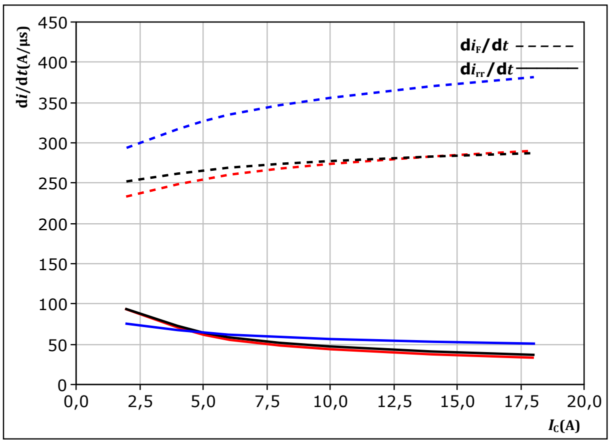
V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
I_C =	10	A		150 °C

Inverter Switching Characteristics

figure 21.	FWD

Typical rate of fall of forward and reverse recovery current as a function of collector current

di_F/dt, di_{rr}/dt = f(I_C)



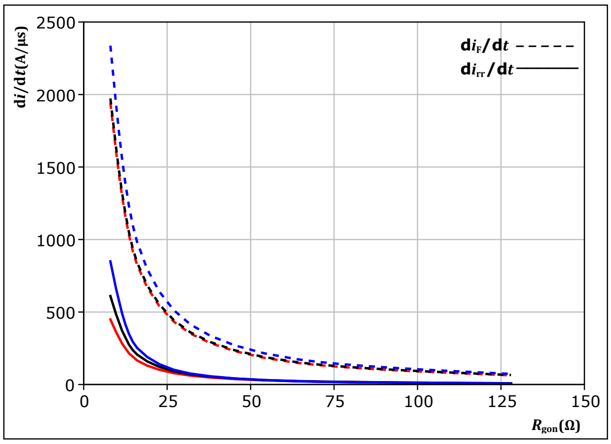
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
R_{gon} =	32	Ω		150 °C

figure 22.	FWD

Typical rate of fall of forward and reverse recovery current as a function of turn on gate resistor

di_F/dt, di_{rr}/dt = f(R_{gon})



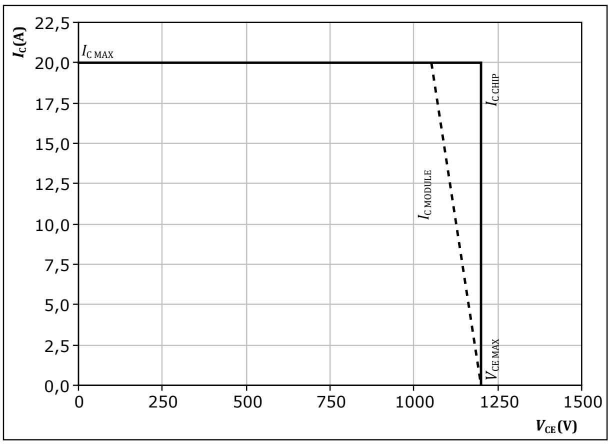
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
I_C =	10	A		150 °C

figure 23.	IGBT

Reverse bias safe operating area

I_C = f(V_{CE})



At			
	T_j =	150	°C
	R_{gon} =	32	Ω
	R_{goff} =	32	Ω

Inverter Switching Definitions

figure 24.	IGBT

Turn-off Switching Waveforms & definition of t_{doff}, t_{Eoff} (t_{tEoff} = integrating time for E_{off})

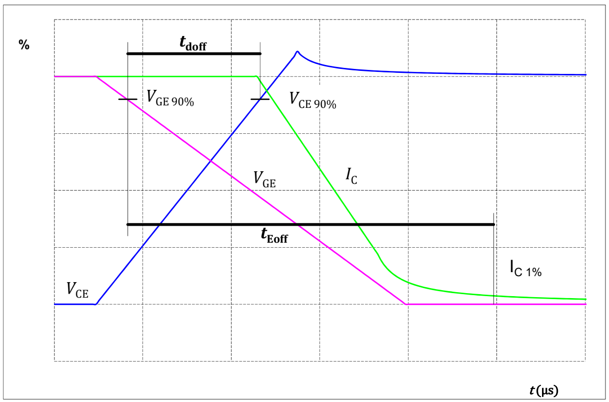


figure 25.	IGBT

Turn-on Switching Waveforms & definition of t_{don}, t_{Eon} (t_{Eon} = integrating time for E_{on})

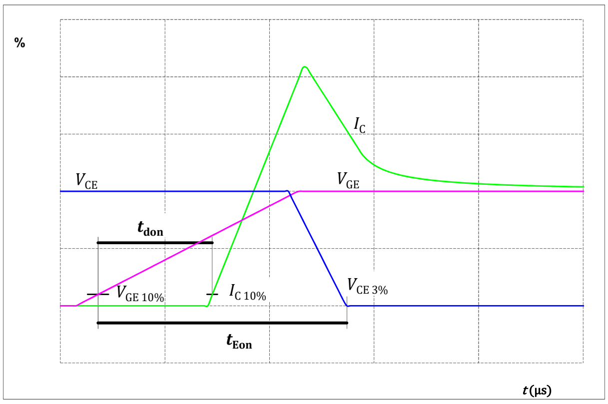


figure 26.	IGBT

Turn-off Switching Waveforms & definition of t_f

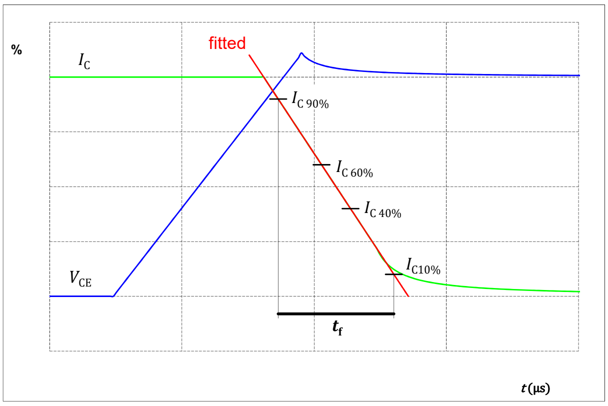
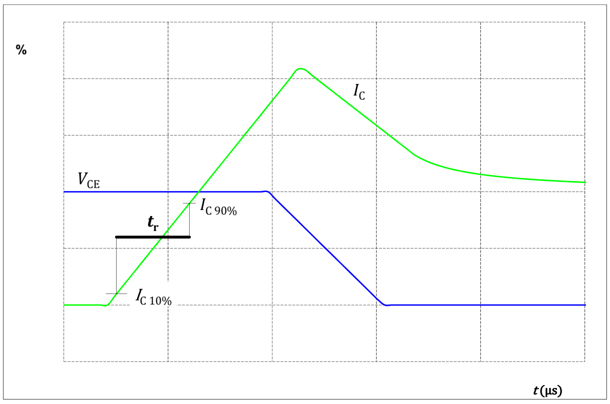


figure 27.	IGBT

Turn-on Switching Waveforms & definition of t_r



Inverter Switching Definitions

figure 28. **FWD**

Turn-off Switching Waveforms & definition of t_{rr}

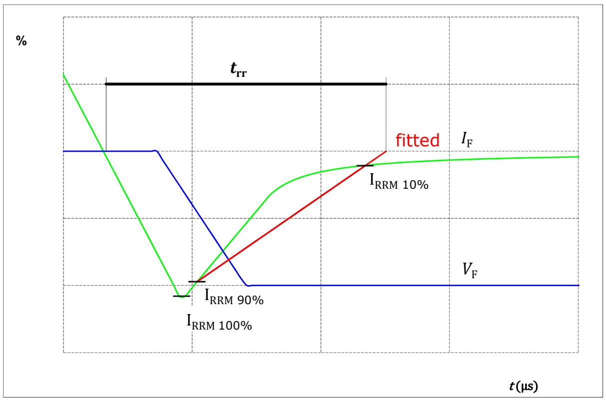
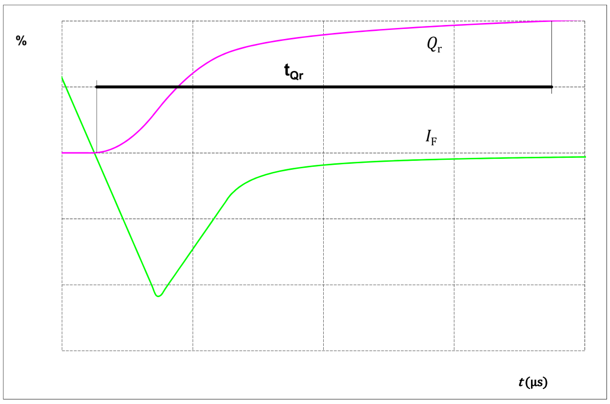


figure 29. **FWD**

Turn-on Switching Waveforms & definition of t_{Qr} (t_{Qr} = integrating time for Q_r)



Ordering Code

Version	Ordering Code
Without thermal paste	10-R1126PA010M7-P707F70
With thermal paste	10-R1126PA010M7-P707F70-/3/

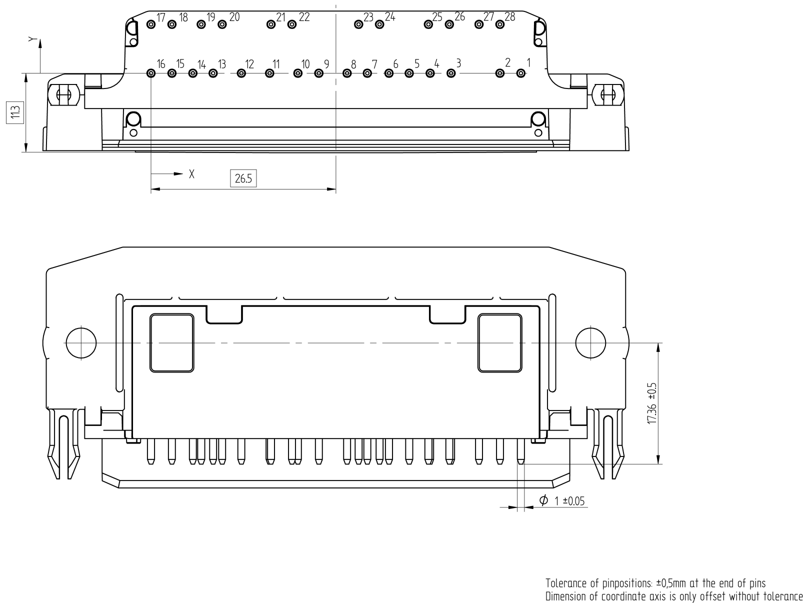
Marking

	Name		Date code	UL & VIN	Lot	Serial
Text	NN-NNNNNNNNNNNNNN-TTTTTTVV		WWYY	UL VIN	LLLLL	SSSS
Datamatrix	**Type&Ver**	**Lot number**	**Serial**	**Date code**		
	TTTTTTTVV	LLLLL	SSSS	WWYY		

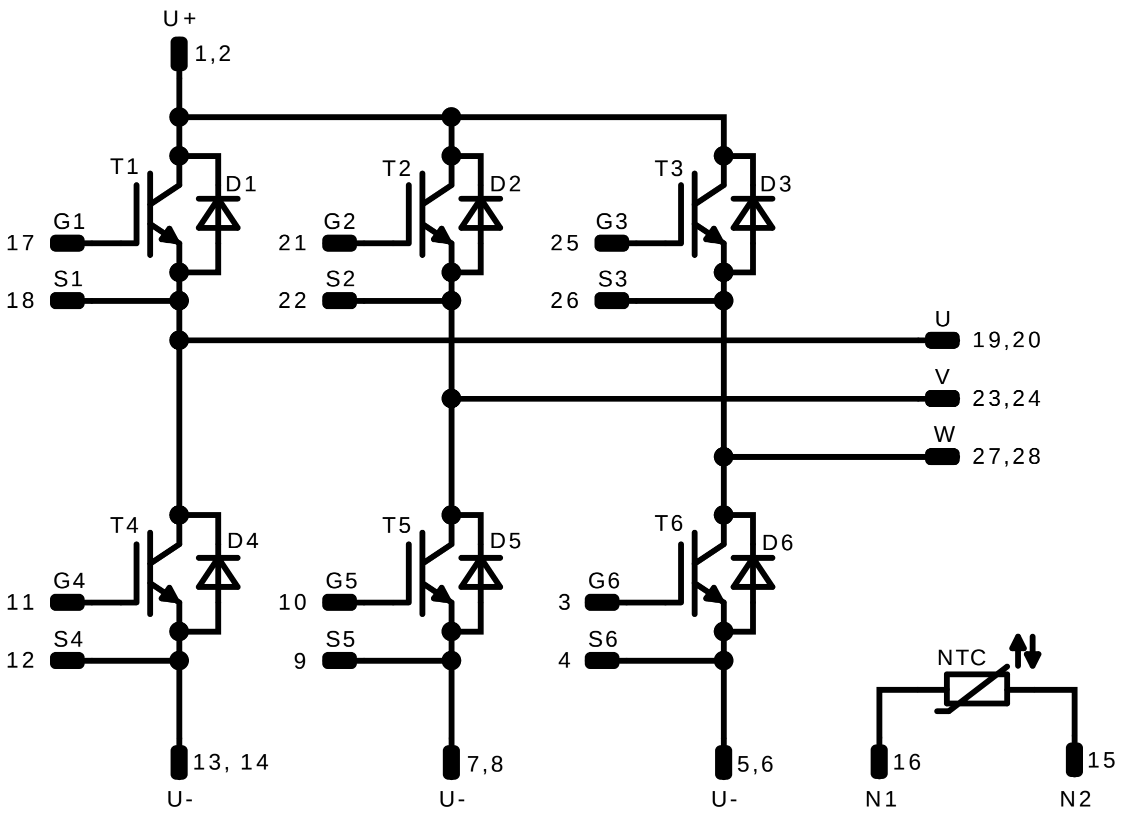
Outline

Pin table [mm]

Pin	X	Y	Function
1	53	0	U+
2	50	0	U+
3	43	0	G6
4	40	0	S6
5	37	0	U-
6	34,1	0	U-
7	31	0	U-
8	28,1	0	U-
9	24,05	0	S5
10	21,05	0	G5
11	17	0	G4
12	12,95	0	S4
13	8,9	0	U-
14	6	0	U-
15	3	0	N2
16	0	0	N1
17	0	7	G1
18	3	7	S1
19	7,2	7	U
20	10,2	7	U
21	17,2	7	G2
22	20,2	7	S2
23	29,75	7	V
24	32,75	7	V
25	39,75	7	G3
26	42,75	7	S3
27	47	7	W
28	50	7	W



Pinout



Identification

ID	Component	Voltage	Current	Function	Comment
T4, T1, T5, T2, T6, T3	IGBT	1200 V	10 A	Inverter Switch	
D1, D4, D2, D5, D3, D6	FWD	1200 V	10 A	Inverter Diode	
NTC	NTC			Thermistor	

Packaging instruction				
Standard packaging quantity (SPQ) 80	>SPQ	Standard	<SPQ	Sample

Handling instruction
Handling instructions for *flow*90 1 packages see vincotech.com website.

Package data
Package data for *flow*90 1 packages see vincotech.com website.

UL recognition and file number
This device is certified according to UL 1557 standard, UL file number E192116. For more information see vincotech.com website.

Document No.:	Date:	Modification:	Pages
10-R1126PA010M7-P707F70-D1-14	7 Jan. 2020		